

ICS 19.040
CCS A 21

SJ

**INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

SJ/T 11200-2016

Replacing SJ/T 11200-1999

**Environmental testing Part 2-58: Tests - Test Td: surface mount
components solderability, dissolution of metallization layers
and resistance to soldering heat resistance test method**

环境试验 2-58部分：试验 试验Td：表面组装元器件可焊性、金属化层耐溶蚀性
和耐焊接热的试验方法

(English Translation)

Issued on: April 5, 2016

Implemented on: September 1, 2016

Issued by: Ministry of Industry and Information Technology

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What this standard covers

This standard applies to surface-assembled components and provides standard test methods for solderability of lead-free solder, eutectic or near-eutectic tin-lead solder, corrosion resistance of metallized layers, and solder heat resistance. It is specified that when the solder bath method is not applicable, the test is performed by reflow soldering.

Document data

International classification (ICS): 19.040.

Chinese classification (CCS): A21.

Estimated length of the Chinese original: 20,271 words.

Adopted international standard: IEC 60068-2-58:2004, MOD.

Supersedes the earlier edition SJ/T 11200-1999.